

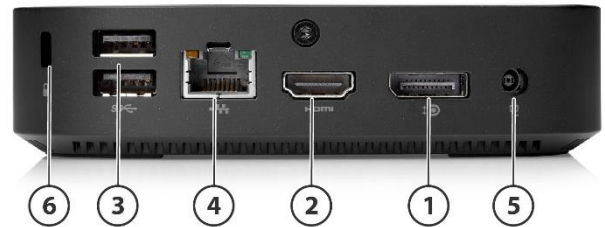
Overview

HP t430 Thin Client

Front View Image



Rear View Image



FRONT

1. Power button
2. Power memory activity indicator LED light

BOTTOM

VESA 100 mounting points located underneath the system's rubber foot pads

BACK

1. DisplayPort™ 1.2 digital video output
2. HDMI digital video output
3. 2 x USB-A 3.1 Gen 1 ports for keyboard/mouse
4. RJ45 Gigabit Ethernet interface
5. 19V DC power input
6. Cable lock slot



SIDE

1. 1 x USB-C™ port, supporting DisplayPort™ over USB-C™ and USB Power Delivery
2. USB-A 3.1 Gen 1 port for accessories
3. 1 x 3.55 mm headset jack

Overview

AT A GLANCE

- Intel® Celeron® Processor N4000; 1.1 – 2.6 GHz dual-core processor
- Embedded DDR4 single-channel SDRAM system memory
 - HP ThinPro models configured with 2 GB
 - Windows models configured with 4 GB
- Embedded solid-state flash memory storage
 - HP ThinPro models configured with 16 GB
 - Windows models configured with 32 GB
- 1 x DisplayPort™, 1 x HDMI and 1 x DisplayPort™ over USB-C™ digital video outputs supporting up to Ultra High Definition (UHD)/4K (3840 x 2160) resolutions.
- Active thermal management technology monitors component operating temperatures, throttles SOC processor if appropriate, and prevents unit thermal shutdown
- Gigabit Ethernet (GbE) network connection supported via an integrated Realtek GbE NIC module and presented with an RJ45 connector on the rear I/O panel
- Optional Wi-Fi/Bluetooth® adapter including antennas integrated internally in the chassis¹.
- USB ports located on the back and side panels, including a USB-C™ 3.1 Gen 1 port that supports DisplayPort™ over USB-C™ and USB Power Delivery
- 3.5 mm headset audio port on side panel that will support a headset, headphones or an external speaker system
- Integrated VESA 100 mounting system; the four threaded holes are conveniently located under the unit's rubber foot pads
- TCG certified Trusted Platform Module (TPM) chipset on Windows models; other security features include a system UEFI designed to address NIST SP 800-147 guidelines, cable lock slot, and power cord retention clip to prevent accidental power cord disconnects
- ENERGY STAR® certified and EPEAT® Gold registered in the United States. See <http://www.epeat.net> for registration status in other countries
- Post-consumer recycled plastics content greater than 25% total unit plastics (by weight)
- Low halogen² material content

¹ Wireless access point and Internet access is required; availability of public wireless access points is limited

² This product is low halogen except for power cords, cables and peripherals; service parts obtained aftermarket may not be low halogen

Warranty

HP Customer Support: limited three-year hardware limited warranty in most regions; HP Care Packs are extended service contracts that go beyond your standard limited warranties; for more details visit <http://www.hp.com/go/cpc>

Technical specifications

OPERATING SYSTEMS

HP ThinPro, including HP Smart Zero Core

Microsoft Windows 10 IoT Enterprise

PROCESSOR

Model	CPU Frequency base/max	x86 Cores	GPU EUs	Cache	GPU	Memory
Intel® Celeron® Processor N4000	1.1/2.6 GHz	2	12	4 MB	Intel® UHD Graphics 600	DDR4 2400

NOTE: CPU Maximum frequency is based on Intel® Turbo Boost Technology

GRAPHICS

Number of displays supported: One or two displays.
NOTE: a maximum of two displays are supported.

1 x HDMI port

Video outputs: 1 x DisplayPort™

1 x DisplayPort™ over USB-C™

NOTE: dual displays are supported using the following video output combinations:

- HDMI + DisplayPort™
- HDMI + DisplayPort™ over USB-C™

Video Resolution Support Matrix

Windows 10 IoT RS1	≤2 x FHD 1920 x 1080 @ 60Hz	1 x UHD/4K 3840 x 2160 @ 60Hz	2 x UHD/4K 3840 x 2160 @ 30Hz
Static screen (no video)	✓	✓	✓
1080p 30fps (or below) video	✓	✓	✓
1080p 60fps video	✓	✓	✓
4k @ 30fps video	✓	✓	
HP ThinPro 6.2	≤2 x FHD 1920 x 1080 @ 60Hz	1 x UHD/4K 3840 x 2160 @ 60Hz	2 x UHD/4K 3840 x 2160 @ 30Hz
Static screen (no video)	✓	✓	✓

Technical specifications

1080p 30fps (or below) video	✓	✓	✓
1080p 60fps video			
4k @ 30fps video			

NOTES:

- 4K video playback is not supported over Virtual Desktop Infrastructure (VDI)
- Only 1 Citrix session can be launched

MEMORY

Type:	Single channel DDR4 SDRAM
Data Transfer Rate (speed):	up to 2,400 MT/s
Peak Transfer Rate (bandwidth):	19,200 MB/s
Number of slots:	0 slots; memory is embedded
Memory Capacity:	2 GB on ThinPro models 4 GB on Windows models
Reserved for graphics:	256 MB (default), 512 MB or 1 GB

NOTE: The system's Graphics Processing Unit (GPU) uses part of total system memory. System memory dedicated to graphics performance is not available for use by other programs

UEFI (Unified Extensible Firmware Interface)

- UEFI Specification Revision: 2.6
- Meets requirements for Common Criteria, an independent third-party certification of trustworthiness
- Meets requirements for FIPS 140-2, a standard for cryptographic integrity
- Designed to address NIST SP800-147 guidelines

TRUSTED PLATFORM MODULE (TPM)

- Trusted Computing Group (TCG) certified TPM 2.0 on Windows 10 IoT Enterprise models

NOTE: HP ThinPro models do not include a TPM

STORAGE

Type:	NAND flash memory; non-volatile
Number of sockets:	0 slots; flash storage is embedded

Technical specifications

Storage Capacity: 16 GB on HP ThinPro models
32 GB on Windows models

INPUT/OUTPUT

USB ports: 1 x USB-C™ featuring DisplayPort™ over USB-C™ and USB Power Delivery
3 x USB-A 3.1 Gen 1 ports; 2 x rear ports, 1 x side port

Video outputs*: 1 x DisplayPort™ 1.2
1 x HDMI
1 x DisplayPort™ over USB-C™

Other: 1 x RJ45 GbE interface
1 x 3.5mm headset jack

NOTE: only 2 video outputs can be used simultaneously

AUDIO/VIDEO

Audio: 3.5 mm headset jack supporting a headset, headphones or and external speaker
Audio CODECs include MP3, AAC stereo, HE AAC
Includes hardware acceleration support
MPEG-4 part 2 (DivX, Xvid)

Video: MPEG-4 part 10 (H.264), Advanced Video Coding (AVC) (H.264 encode)
MPEG-H part 2, High Efficiency Video Coding (HEVC) (H.265. decode)
WMV 7/8/9 VC-1 & ASF Demuxer
Includes hardware acceleration support

HARDWARE SECURITY

- Security lock support (cable lock sold separately)
 - Trusted Platform Module (TPM) on Windows models
-

NETWORKING

Wired networks: Realtek Gigabit Ethernet (GbE)
Wake on LAN
PXE
TCP/IP with DNS DHCP
Secure Socket Tunneling Protocol (SSTP); supported with a Microsoft operating system

Wireless networks: Intel® Wireless-AC 9260 with Bluetooth®; M.2 module with integrated internal Wi-Fi antenna system

NOTE: Wireless access point and Internet access required. Availability of public wireless access point may be limited. Wireless features, performance and support may vary depending on environmental variables such as placement, settings and firmware of the access point. Contact your wireless vendor for support.

Technical specifications

SOFTWARE SUPPORT			
Host Environment	Protocol	HP ThinPro HP Smart Zero Core	MS Win10 IoT
Microsoft Remote Desktop Services	Remote FX (RFX), RDP	✓	✓
Citrix®	ICA, HDX	✓	✓
VMware® Horizon™	RDP, PCoIP, Blast Extreme	✓	✓

Protocol Clients	HP ThinPro HP Smart Zero Core	MS Win10 IoT
Citrix Receiver™	✓	✓
Microsoft Remote Desktop Client		✓
VMware® Horizon View™ Client	✓	✓
HP TeemTalk Terminal Emulator	✓	
Free RDP	✓	

Browser Support	HP ThinPro HP Smart Zero Core	MS Win10 IoT
Mozilla Firefox	50.0.1	
Internet Explorer		11

Security	HP ThinPro HP Smart Zero Core	MS Win10 IoT
SmartCard	✓	✓
Logon Manager	✓	✓
Read-only operating system	✓	✓
802.1x	✓	✓
Operating system write filter		HP Write Manager Microsoft Unified Write Filter
Microsoft Firewall		✓

Management Tools	HP ThinPro HP Smart Zero Core	MS Win10 IoT
HP Device Manager	✓	✓
HP ThinUpdate		✓
HP Easy Tools	✓	

Technical specifications

HP Smart Zero Client Services	✓	
Microsoft SCCM/EDM agent		✓

Additional Components	HP ThinPro HP Smart Zero Core	MS Win10 IoT
HP Easy Shell		✓
Windows Media Player		12
Microsoft Direct Access		✓
Microsoft BranchCache		✓
Microsoft AppLocker		✓
Microsoft Sideload		✓

NOTE: Software performance and support may vary depending on customer environment and backend.

Audio/Video CODEC	HP ThinPro HP Smart Zero Core	MS Win10 IoT
MP3	✓	✓
WMA Stereo	✓	✓
AAC stereo & HE AAC	✓	✓
Microsoft AC3 encoder		12
MPEG-1		✓
MPEG-4 part 2 (DivX, Xvid, H.263)	✓	✓
MPEG-4 part 10 (H.264, AVC)	✓	✓
WMV 7/8/9/ VC-1 & ASF Demuxer	✓	✓

NOTE: Software performance and support may vary depending on customer environment and backend.

WEIGHTS & DIMENSIONS

W x D x H	135 x 135 x 32 mm
Volume	0.58 liter
System Weight	416 g (0.92 lb)
Shipping Weight	1270 g (2.80 lb.)

NOTE: All measurements are approximate; the addition of optional modules will increase the weight

POWER SUPPLY

Technical specifications

45W external power adapter
 Worldwide auto-sensing 100-240 VAC, 50-60 Hz
 Energy saving automatic power-down
 Surge tolerant

AGENCY COMPLIANCE

Accessibility: Section 508 Accessibility. VPAT report available
 Environmental Stewardship: Worldwide (ENERGY STAR®, EPEAT®, ROHS, ERP, TCO, MEPS, CECP, HP GSE, etc.)
 Product Safety: Worldwide (UL, CB, GS, CCC, etc.)
 Electromagnetic Compliance (EMC): Worldwide(FCC/CISPR/EN/VCCI/ICES/AS/NZS/CNS/KCC) “Class B” EMI regulations

ENVIRONMENTAL

Operating Temperature Range: 50° to 104° F (10° to 40° C)
 Non-operating Temperature Range: -22° to 140° F (-30° to 60° C)
 Humidity: Condensing: 20% to 80%
 Non-condensing: 10% to 90%

NOTE: Specifications are at sea level with altitude derating of 1° C/300m (1.8° F/1000ft) to a maximum of 3 Km (10,000 ft), with no direct, sustained sunlight. Upper limit may be limited by the type and number of options installed.

Eco-Label Certifications & declarations This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- ENERGY STAR®
- EPEAT® Gold registered in the United States. See <http://www.epeat.net> for registration status in your country.
- IT ECO declaration

Energy Consumption

(in accordance with US ENERGY STAR® test method)

	115 V ac, 60 Hz	230 V ac, 50 Hz	100 V ac, 50 Hz
Normal Operation (Short idle)	3.44 W	3.48 W	3.48 W
Normal Operation (Long idle)	2.67 W	2.64 W	2.71 W
Sleep	0.60 W	0.66 W	0.58 W
Off	0.58 W	0.66 W	0.58 W

Heat Dissipation*

	115 V ac, 60 Hz	230 V ac, 50 Hz	100 V ac, 50 Hz
Normal Operation (Short idle)	12 BTU/hr	12 BTU/hr	12 BTU/hr
Normal Operation (Long idle)	9 BTU/hr	9 BTU/hr	9 BTU/hr
Sleep	2 BTU/hr	2 BTU/hr	2 BTU/hr
Off	2 BTU/hr	2 BTU/hr	2 BTU/hr

NOTE:Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Technical specifications

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive -2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT®) standard at the gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO 11469 and ISO1043.
- This product contains 5.65 % post-consumer recycled plastic (by wt.)
- This product is 93.1 % recycle-able when properly disposed of at end of life.

Packaging Materials

External:	PAPER/Corrugated	402 g
Internal:	PLASTIC/EPE	33 g
	PLASTIC/LDPE	39 g

RoHS Compliance

HP Inc. is committed to compliance with all applicable environmental laws and regulations, including the European Union Restriction of Hazardous Substances (RoHS) Directive. HP's goal is to exceed compliance obligations by meeting the requirements of the RoHS Directive on a worldwide basis. By July 1, 2006, RoHS substances will be virtually eliminated (virtually = to levels below legal limits) for all HP electronic products subject to the RoHS Directive, except where it is widely recognized that there is no technically feasible alternative (as indicated by an exemption under the EU RoHS Directive).

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants – may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)

Technical specifications

- Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: <http://www.hp.com/go/reuse-recycle> or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the HP Inc. web site at: <http://www.hp.com/go/recyclers>. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP, Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

Global Citizenship Report

<http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html>

Eco-label certifications

<http://www.hp.com/hpinfo/globalcitizenship/environment/productdesign/ecolabels.html>

ISO 14001 certificates:

<http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842>
and

<http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf>

Summary of Changes

Date of change:	Version History:	Type of change	Description of change:
June 18, 2018	From v1 to v2	Update	Input/Output, Weights & Dimensions
July 24, 2018	From v2 to v3	Update	Environmental section
August 20, 2018	From v3 to v4	Changed	Software support for VMware Horizon
September 10, 2018	From v4 to v5	Changed	Format

© 2018 HP Development Company, L.P. The information contained herein is subject to change without notice. The only warranties for HP products and services are set forth in the express limited warranty statements accompanying such products and services. Nothing herein should be construed as constituting an additional warranty. HP shall not be liable for technical or editorial errors or omissions contained herein. AMD and Radeon are trademarks of Advanced Micro Devices, Inc. DisplayPort™ and the DisplayPort™ logo are trademarks owned by the Video Electronics Standards Association (VESA®) in the United States and other countries. Amazon Web Services, the “Powered by Amazon Web Services” logo, and Amazon WorkSpaces are trademarks of Amazon.com, Inc. or its affiliates in the United States and/or other countries. Bluetooth® is a trademark owned by its proprietor and used by HP Inc. under license. ENERGY STAR is a registered trademark owned by the U.S. Environmental Protection Agency. Linux® is the registered trademark of Linus Torvalds in the U.S. and other countries. Microsoft and Windows are either registered trademarks or trademarks of Microsoft Corporation in the United States and/or other countries. Intel® is a trademark of Intel Corporation in the U.S. and other countries. VMware Horizon and VMware Horizon View are registered trademarks or trademarks of VMware, Inc. in the United States and/or other jurisdictions. Citrix and Citrix Receiver are trademarks of Citrix Systems, Inc. and/or one more of its subsidiaries, and may be registered in the United States Patent and Trademark Office and in other countries.